





PNP SILICON EPITAXIAL PLANAR TRANSISTORS

BC556_BC560

TO-92 Plastic Package



For switching and AF amplifier application

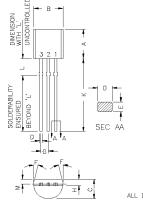
ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless specified otherwise)

ABSOLUTE MAXIMUM (ATTIVOS (1 ₈ –23 C diffess specified otherwise)							
DESCRIPTION	SYMBOL	BC556	BC557	BC560	BC558	BC559	UNITS
Collector Base Voltage	V_{CBO}	80	50)	3	80	V
Collector Emitter Voltage	V_{CEO}	65	45	,	3	80	V
Emitter Base Voltage	V_{EBO}			5			V
Collector Current (DC)	I _C	100		mA			
Collector Current - Peak	I _{CM}	200		mA			
Power Dissipation	P _{tot}	500		mW			
Storage Temperature	T _{stg}	- 65 to +150		°C			
Junction Temperature	T _j	150			°C		

Characteristics at Ta = 25°C

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
		I _C =2mA, V _{CE} =5V	75	800	
DC Current Gain	h _{FE}	A	110	220	-
		В	200	450	-
		I _C =10mA, I _B =0.5mA	420	0.30	- V
Collector Emitter Saturation Voltage	$V_{CE(Sat)}$. –	-		V
		I _C =100mA, I _B =5mA	- 0.55	0.65	·
Base Emitter on Voltage	$V_{BE(on)}$	$I_C=2mA$, $V_{CE}=5V$	0.55	0.75	V
	- BE(OII)	I _C =10mA, V _{CE} =5V	-	0.82	V
Collector Base Cut off Current	I _{CBO}	$V_{CB}=30V$, $I_{E}=0$	-	15	nA
Emitter Base Cut off Current	I _{EBO}	V _{EB} =5V	-	100	nA
Collector Base Breakdown Voltage					
BC556	\ /	1 400-4	80	-	
BC557, BC560	$V_{(BR)CBO}$	I _C =100μA	50	-	V
BC558, BC559			30	-	
Collector Emitter Breakdown Voltage					
BC556	V	I _c =2mA	65	-	
BC557, BC560	$V_{(BR)CEO}$	IC-ZIIIA	45	-	V
BC558, BC559			30	-	
Emitter Base Breakdown Voltage	V _{(BR)EBO}	I _E =100μA	5	-	V
Transition Frequency	f _T		100	-	MHz
Collector Base Capacitance	C _{cb}	V _{CB} =10V, f=1MHz	-	6.0	pF

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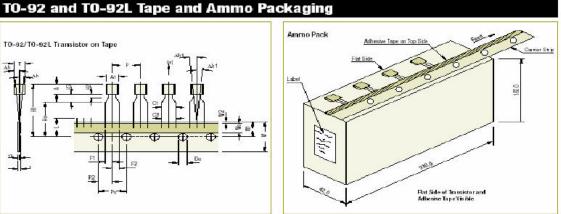
	DIM	MIN	MAX			
	A	4.30	5.33			
	В	4.10	5.20			
	С	3.10	4.19			
	D	0.35	0.55			
	E	0.29	0.55			
	F	8 DEG				
	G	1.14	1.40			
	Н	1.00	1.80			
	K	11.50	-			
	L	1.982	2.082			
	М	1.03	1.53			
ALL	ALL DIMENSIONS ARE IN mm					

Packaging Specifications

T & A: Tape and Ammo Pack; T & R: Tape and Reel; Bulk; Loose in Poly Bacs; Tube: Tube and Carton; K: 1,000

Package / Case Type	Packaging Type	Std. Packing	Inner Carton			Outer Carton		
	Oty	Qty	Size L x W x H	Gross Weight	Oty	Size L x W x H	Gross Weight	
				(cm)	(Kg)		(em)	(Kg)
T0-92	Bulk	1,000	5K	19 x 19 x 8	1.1	80K	43 x 40 x 35	20.0
	T&A	2,000	2K	32 x 4.5 x 20	0.7	40K	43 x 40 x 35	15.2

TO-92/TO-921 Transistor on Tape



Tape Specifications

Item description	Symbo
Body width	A1
Body height	A
Body thickness	T
Pitch of component ^{Cr}	P
Feed hole pitch ⁵¹	Po
Feed hole center to	
component centre ⁵²	P2
Comp. alignment, Side view ⁶⁻³	Dh
Comp. alignment, Front view ⁶³	Dhri
Tape width ^{or}	W
Hold down tape width ^{or}	We
Hole position	W1
Hold-down tape position	W2
Lead wire of not height	Ho
Component height	Ht
Length of snipped leads	L
Feed hole diameter ^c r	Do
Total tape thickness ⁵⁴	t
Lead-to-lead distance ^{Cr}	F1,F2
Stand off	H2
Clinch height	H3
Lead parallelism@r	C1-02
Pull-out force	(p)

Min	Nom	Max	Tol
4.45		5.20	
4.32		5.33	
3.18		4.19	
	12.7		±1.0
	12.7		±0.3
	6.35		±0.4
	0	1.0	
	0	1.3	
	18	4	±0.5
	6		±0.2
	9		+0.7 -0.5
0.0		0.7	
	16		±0.5
		24.0	
		11.0	
	4		±0.2
		1.2	
2.4		2.7	
0.45		1.45	
		3.0	
		0.22	
6N			

Min	Nom	Max	Tol
4.7		5.1	
7.8		8.2	
3.7		4.1	
-0.000	12.7	- 3200	±0.3
	12.7		±0.2
	6.35		±0.3
	0		±1.0
	0		±1.0
	18.0		+1.0 -0.5
	6.0		±0.5
	9.0		±0.5
		1.0	
	16.0		±0.6
		29.0	
		11.0	
	4.0		±0.2
	0.2		±0.5
2.2		2.8	
0.45		1.45	
		4.0	
		0.22	
GM			

- Maximum alignment deviation between leads not to be greater than 0.20 mm.
- Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
- Hold down tape not to exceed beyond the edge(s) carrier tape and there shall be no exposure of adhesive.
- No more than 3 consecutive missing components is permitted.
- A tape trailer, having at least three feed holes is required after the last
- compenent. Splices shall not interfere with the sprocket feed holes.
- §1 Cumulative pitcherner 1.0 mm/20 pitch. §2 To be measured at bottom of cinch. §3 At top of bady. §4 H = 0.3 0.0 mm Or Critical Dimension.

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Customer Notes BC556_BC560

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Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

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